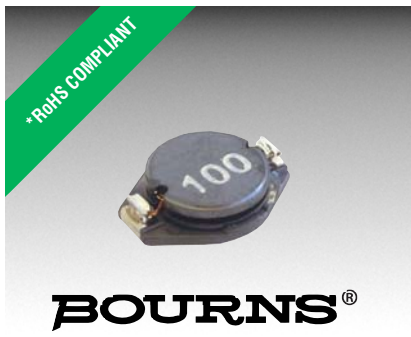




Features

- Formerly J.W. Miller® model
- Height of 3.0 mm max.
- Current rating up to 2.0 A
- RoHS compliant*

Applications

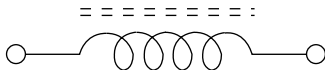
- Input/output of DC/DC converters
- Industrial electronics
- Power supplies for:
 - Portable communications equipment
 - Camcorders
 - LCD TVs
 - Car radios

PM3308 Series - SMD Power Inductors

Electrical Specifications

Bourns Part No.	Inductance 100 kHz		Test Frequency (MHz)	DCR Max. (mΩ)	I _{rms} (A)	I _{sat} (A)
	(μH)	Tol. (%)				
PM3308-100M-RC	10	±20	2.52	0.11	2.00	2.40
PM3308-150M-RC	15	±20	2.52	0.15	1.50	2.00
PM3308-220M-RC	22	±20	2.52	0.23	1.30	1.60
PM3308-330M-RC	33	±20	2.52	0.30	1.10	1.40
PM3308-470M-RC	47	±20	2.52	0.39	0.80	1.00
PM3308-680M-RC	68	±20	2.52	0.7	0.70	0.90
PM3308-101M-RC	100	±20	0.796	0.8	0.60	0.70
PM3308-151M-RC	150	±20	0.796	1.2	0.50	0.60
PM3308-221M-RC	220	±20	0.796	1.9	0.40	0.50
PM3308-331M-RC	330	±20	0.796	2.7	0.30	0.40
PM3308-471M-RC	470	±20	0.796	4.0	0.20	0.30
PM3308-681M-RC	680	±20	0.796	5.3	0.10	0.20
PM3308-102M-RC	1000	±20	0.252	8.4	0.05	0.10

Electrical Schematic



Typical Part Marking



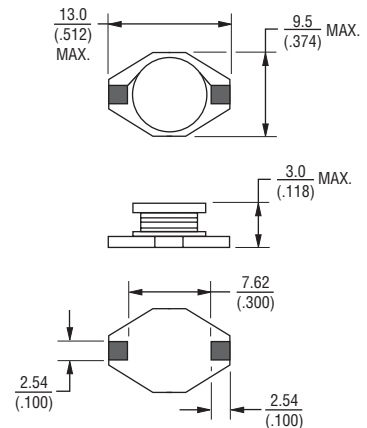
General Specifications

Test Voltage 0.1 V
 Reflow Soldering ... 230 °C; 50 sec. max.
 Operating Temperature
 -55 °C to +125 °C
 (Temperature rise included)
 Storage Temperature ... -55 °C to +125 °C
 Resistance to Soldering Heat
 260 °C, 10 sec. max.

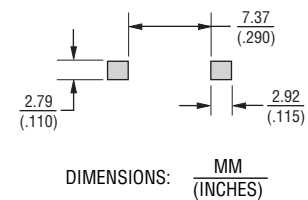
Materials

Core Ferrite
 Wire Enamelled copper
 Terminal Sn/Ni/Cu
 Rated Current
 Ind. drop 10 % typ. at I_{sat}
 Temperature Rise
 30 °C typical at I_{rms}
 Packaging 1000 pcs. per reel

Product Dimensions



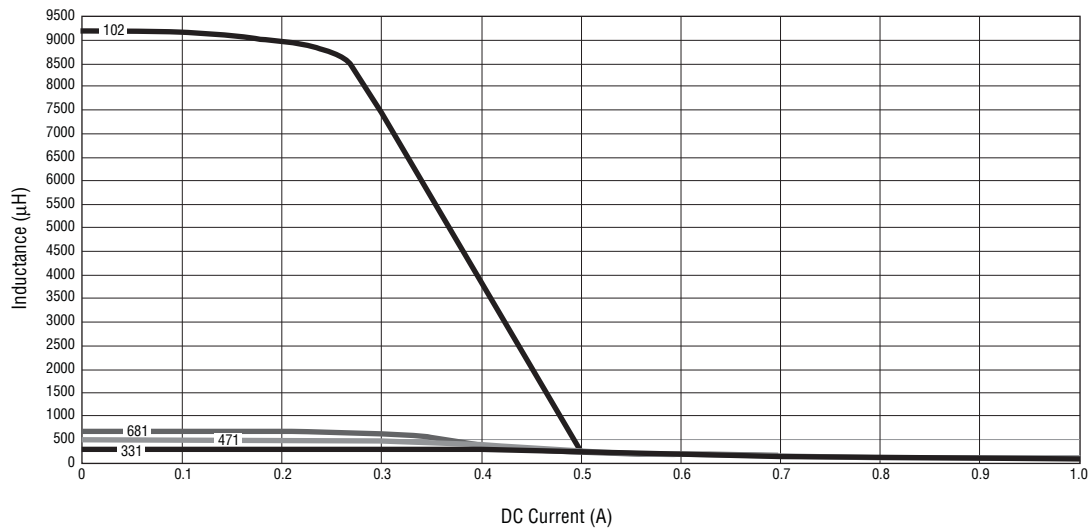
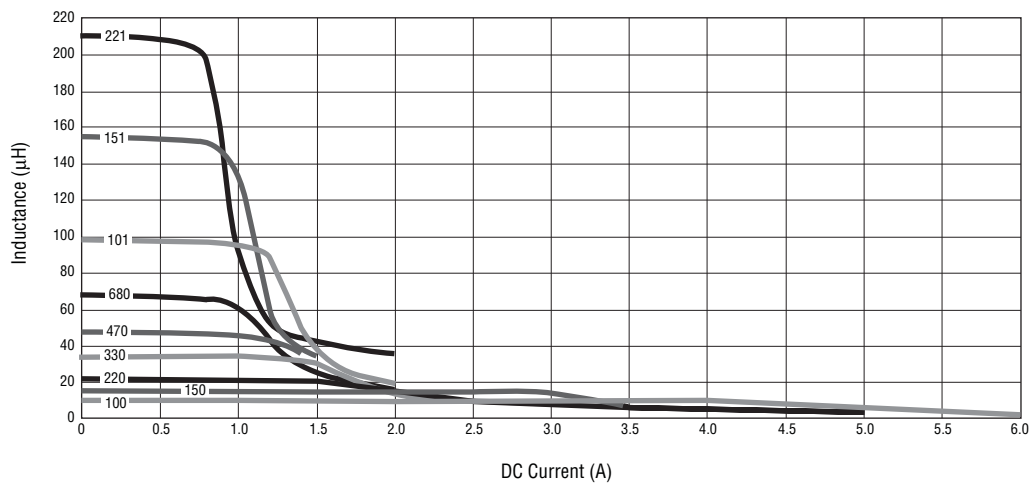
Recommended Pad Layout



PM3308 Series - SMD Power Inductors

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Inductance vs. Current

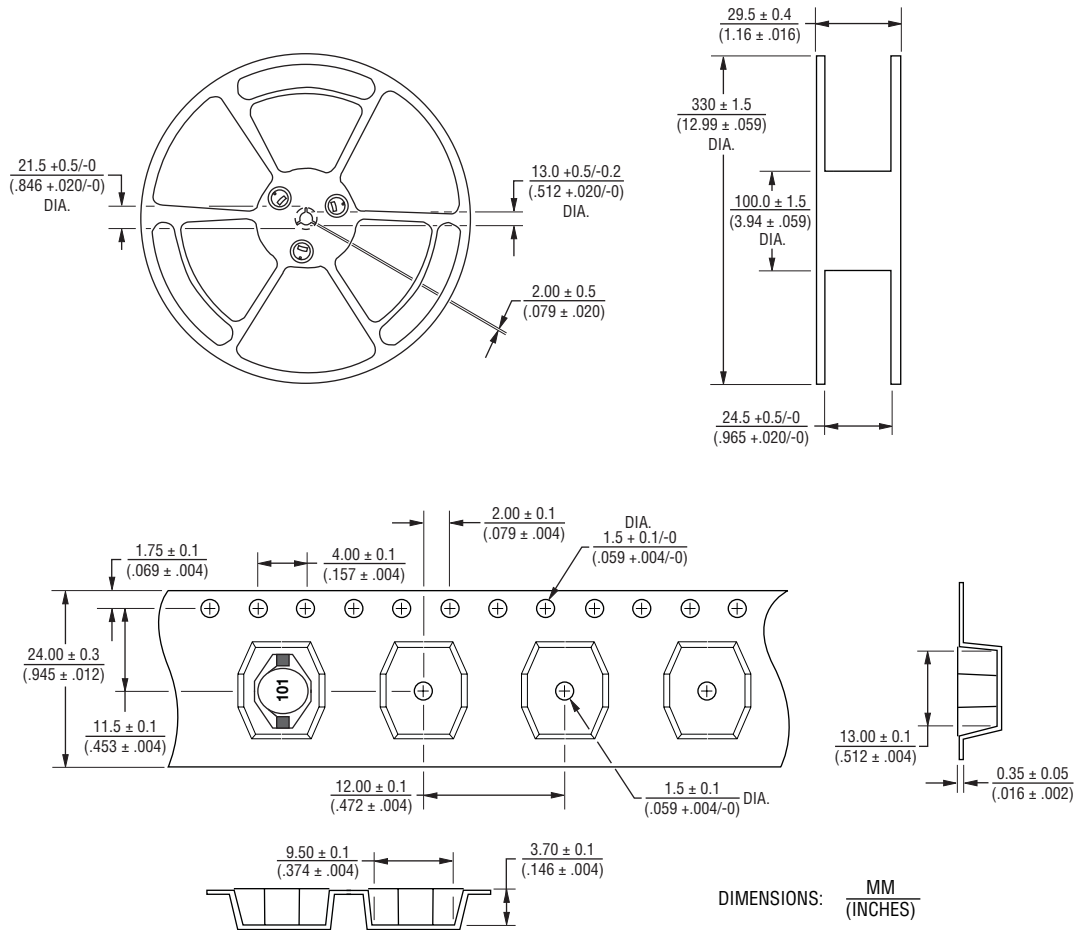


Specifications are subject to change without notice.
Customers should verify actual device performance in their specific applications.

PM3308 Series - SMD Power Inductors

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Packaging Specifications



QUANTITY: 1000 PCS. PER REEL

01/08

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